



MC33926PNB 5A H-Bridge Cold Test Insertion Elimination Report

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1. Objective

This report describes the MC33926PNB PQFN Cold Temperature Test removal plan and results.

Current Test Flow:

Room Probe Test -> Hot Temp Testing -> Cold Temp Testing

Proposed Test Flow:

Room Probe Test -> Hot Temp Testing

2. General Information

Product Family: MC33926PNB/R2

Package : 8x8 32LD PQFN

Test Site : Freescale TJN-FM Tianjin, China

3. Qualification Plan

Cold Temperature Test Elimination evaluation was performed on 100K units of MC33926PNB. Units were sourced from a minimum of 3 wafer lots and 10 assembly lots from the same Fab and mask set.

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4. Qualification Results: Lots and Data Summary

Test elimination evaluation of 100k units resulted in test enhancements at the remaining test insertions. No rejects were reported at the end of this evaluation.

5. Final Verification Steps:

100K parts were tested with the final test program. The test program enhancements ensured all rejects were contained.

6. Product Quality Customer Return Assessment

No customer returns have been seen for MC33926PNB for cold temperature issues.

7. Temperature Variation Analysis/Characterization

Product characterization on material with typical variation of the wafer fabrication process window show that they are containable with the remaining test insertions.

8. Data analysis and verification summary

From above data, it has been verified that requirements and acceptance criteria were achieved. Cold temperature test insertion can be eliminated from the final test flow for MC33926PNB devices.



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